

Electronic Patent Application Fee Transmittal

Application Number:	10826713			
Filing Date:	16-Apr-2004			
Title of Invention:	Wafer-level assembly method for chip-size devices having flipped chips			
First Named Inventor:	William D. Boyd			
Filer:	Yingsheng Tung/Jackie McBride			
Attorney Docket Number:	TI-37214			

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Extension - 2 months with \$0 paid	1252	1	450	450
------------------------------------	------	---	-----	-----

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				450